Job Title: Power Electronics Packaging Engineer  
Location: Canada-ON-Ottawa

Job Description
The Power Electronics Packaging Engineer will be responsible for designing the packaging of advanced, discrete high power GaN products, acting as the key technical interface between multiple suppliers and GaN Systems' internal design teams. In particular, this individual will be responsible for the package design and release to manufacturing for various power electronic products, including transistors, diodes and integrated multi-die solutions. This position is based in our Ottawa office.

Responsibilities include:
- Package design of high speed GaN power electronic products
- Characterization of package materials and manufacturing processes
- Design validation and analyzing failure mechanisms.
- Significant cross-functional interaction is a key part of the job, working with designers, engineers, and product managers.
- Periodic domestic and international travel

Skills and experience:
Required:
- Minimum 8 years of experience in semiconductor packaging
- Background in packaged IC assembly technologies, preferably including: flip-chip; PQFN; ceramic; embedded; lead frame; RDL; wafer bumping; multi-chip module assembly; PCB and sub-assemblies
- Proficient in AutoCAD and SolidWorks 3D, including mechanical/thermal analysis with FEA tools
- Very good written and spoken English language skills: ability to speak clearly in technical discussions, as well as read and write as relating to advanced scientific and technical material.
- Ability to work well with internal team members
- Ability to effectively present information to management, co-workers, and suppliers

Desired:
- Experience in power electronic packaging would be highly desirable
- Experience working with external off shore suppliers

Education:
- Bachelor’s degree in Engineering (or higher)

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